R6007RND3

Nch 600V 7A Power MOSFET

Datasheet

V _{DSS} (@Tj max.)*5	650V
R _{DS(on)} (Max.)	0.940Ω
 DP ^{*2}	±21A
P _D	96W

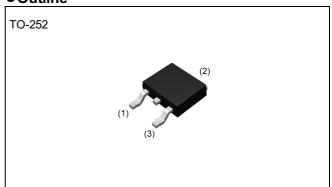
●Features

- 1) Fast reverse recovery time (trr)
- 2) Low on-resistance
- 3) Fast switching speed
- 4) Drive circuits can be simple
- 5) Pb-free plating; RoHS compliant

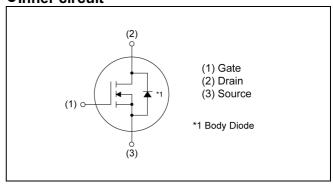
Application

Switching

Outline



•Inner circuit



Marking	R6007RND3

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	600	V
Continuous drain current (T _c = 25°C)	I _D *1	±7	А
Pulsed drain current	I _{DP} *2	±21	А
Gate - Source voltage	V_{GSS}	±30	V
Avalanche current, single pulse	I _{AS} *3	1.6	А
Avalanche energy, single pulse	E _{AS} *3	132	mJ
Power dissipation (T _c = 25°C)	P _D	96	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Dougranton	O	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	1.29	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	50	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Electrical characteristics (T_a = 25°C)

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	600	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 600V, V _{GS} = 0V	-	-	100	μA
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30 V, V_{DS} = 0 V$	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 1.0 \text{mA}$	5.0	6.0	7.0	V
Static drain - source on - state resistance	R _{DS(on)} *5	V _{GS} = 15V, I _D = 3.5A	-	0.730	0.940	Ω
Gate resistance	R_{G}	f = 1MHz, open drain	-	2.9	-	Ω

● Electrical characteristics (T_a = 25°C)

Davanastav	Cy week ed	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 100V	-	460	-	
Output capacitance	C _{oss}	f = 1MHz	-	23	-	
Effective output capacitance energy related	C _{o(er)} ⁶	V _{GS} = 0V	-	21	-	pF
Effective output capacitance time related	C _{o(tr)} ⁷	V _{DS} = 0V to 480V	-	83	1	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300V$, $V_{GS} = 15V$	-	14	-	
Rise time	t _r *5	I _D = 3.5A	-	12	-	
Turn - off delay time	t _{d(off)} *5	R _L ~ 85.7Ω	-	30	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	22	-	

• Gate charge characteristics ($T_a = 25$ °C)

Darameter	Cumb al	Conditions	Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≃ 300V	-	17.5	-	
Gate - Source charge	Q _{gs} *5	I _D = 7A	-	5.1	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 15V	-	6.4	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300V$, $I_D = 7A$	_	9.5	-	V

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Cumb ol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Source current	I _S *1	T _C = 25°C	-	-	7	Α	
Pulsed source current	I _{SP} *2	1C - 23 C	-	1	21	Α	
Source-Drain voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 7A$	-	-	1.7	V	
Reverse recovery time	t _{rr} *5	V _{DD} ≃ 300V	-	50	-	ns	
Reverse recovery charge	Q _{rr} *5	I _S = 7A	-	125	-	nC	
Peak reverse recovery current	_{rr} *5	di/dt = 100A/μs	-	5	-	Α	

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10µs, Duty cycle \leq 1%

^{*3} L \simeq 100mH, V_{DD} = 50V, R_G = 25 Ω , starting T_i = 25°C

^{*4} Tc=25°C

^{*5} Pulsed

^{*6} Co(er) is a fixed capacitance that gives the same stored energy as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .

^{*7} Co(tr) is a fixed capacitance that gives the same charging time as Coss while V_{DS} is rising from 0 to 80% V_{DSS} .

Fig.1 Power Dissipation Derating Curve

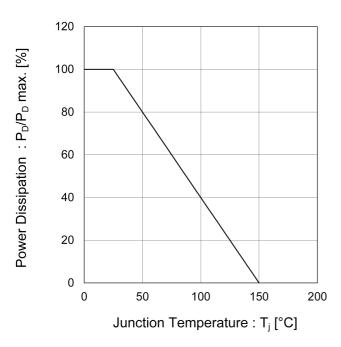


Fig.2 Drain Current Derating
Curve vs. Junction Temperature

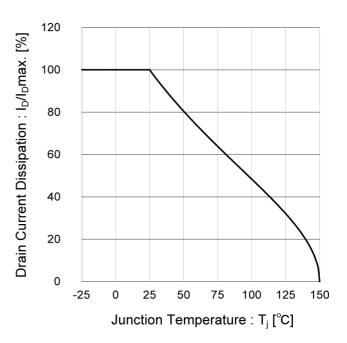


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

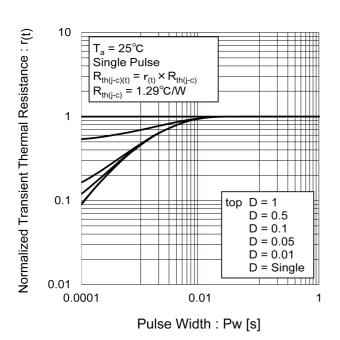


Fig.4 Maximum Safe Operating Area

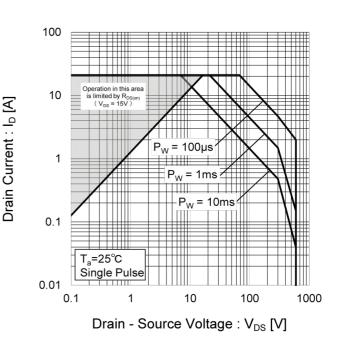


Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

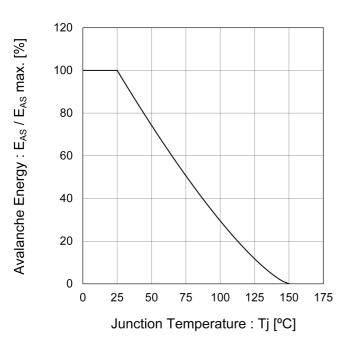


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

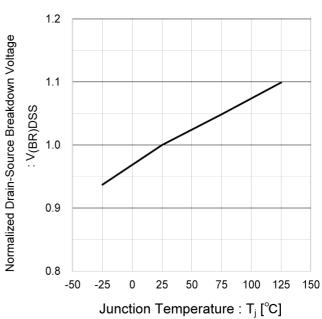
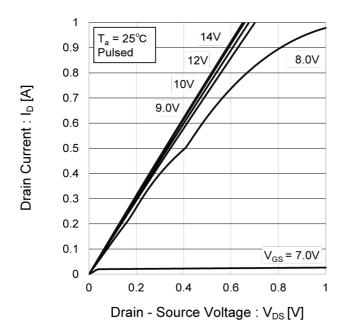


Fig.7 Typical Output Characteristics(I)



Drain Current : I_D [A]

7 T_a = 25°C 10V 14V Pulsed 6 12V 5 9.0V 4 3 2 8.0V 1 $V_{GS} = 7.0V$ 0 1 3 5 0 4 6 Drain - Source Voltage : V_{DS} [V]

Fig.8 Typical Output Characteristics(II)

Fig.9 Typical Transfer Characteristics

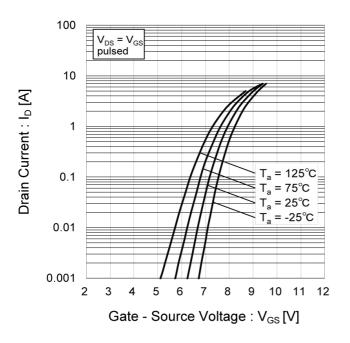


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

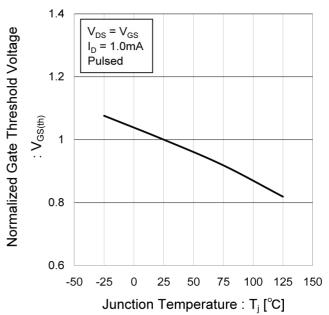


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

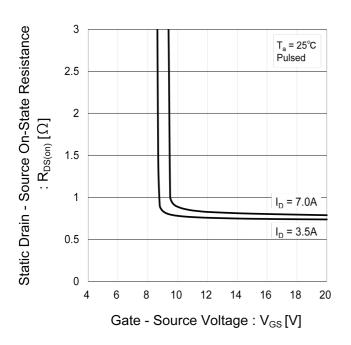


Fig.12 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

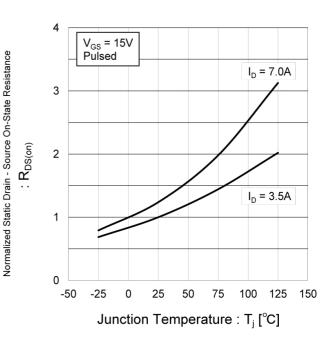


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

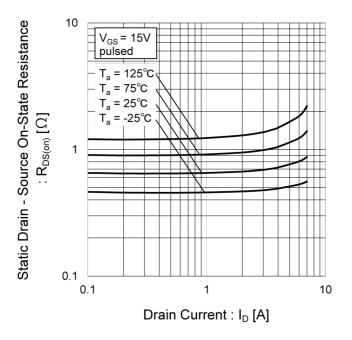


Fig.14 Typical Capacitance vs.
Drain - Source Voltage

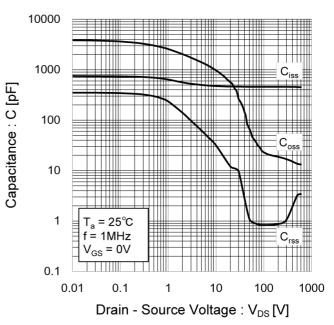


Fig.15 Typical Coss Stored Energy

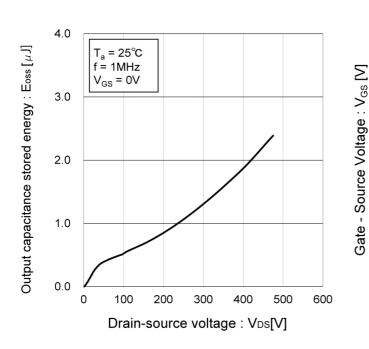


Fig.16 Typical Gate Charge

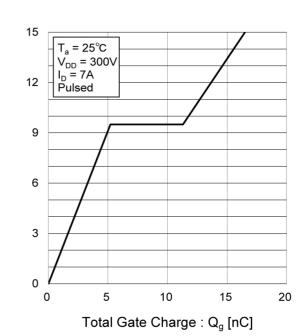


Fig.17 Source Current vs. Source - Drain Voltage

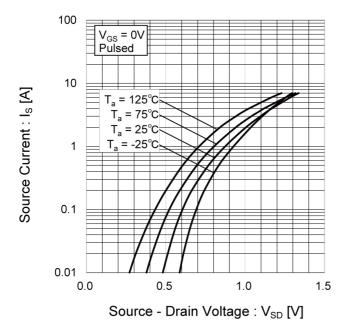
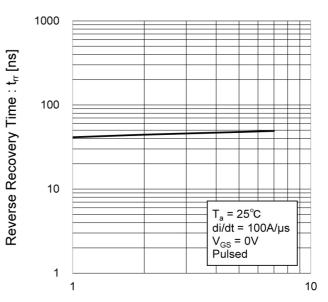


Fig.18 Reverse Recovery Time vs. Source Current



Source Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

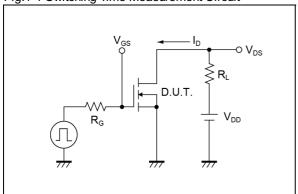


Fig.2-1 Gate Charge Measurement Circuit

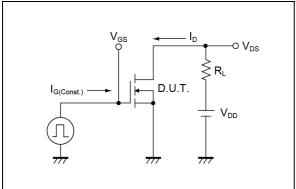


Fig.3-1 Avalanche Measurement Circuit

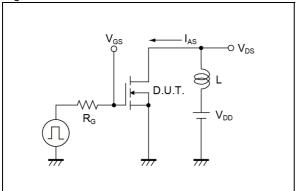


Fig.4-1 Diode Recovery Measurement Circuit

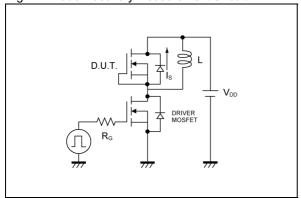


Fig.1-2 Switching Waveforms

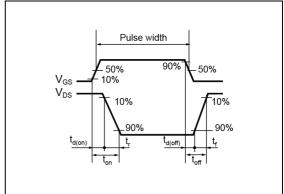


Fig.2-2 Gate Charge Waveform

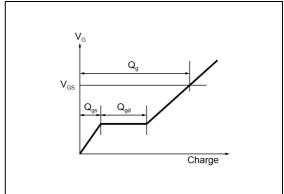


Fig.3-2 Avalanche Waveform

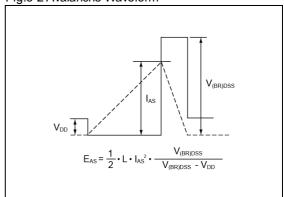
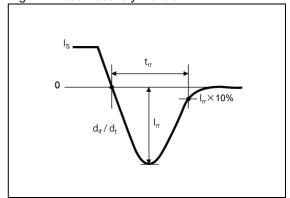
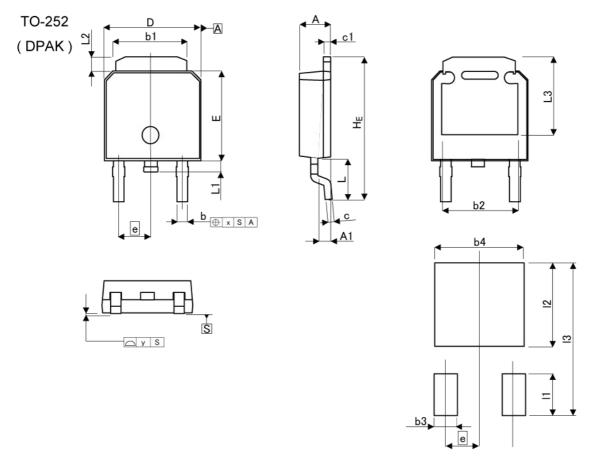


Fig.4-2 Diode Recovery Waveform



Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	189
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.1	114
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
Х	-	0.25	(=)	0.010
у	-	0.10	,-,;	0.004
D.11.4	MILIMETERS		TERS INCHES	
DIM	MIN	MAX	MIN	MAX
b3	-	1.15	-	0.045
b4	-	5.55	. . .	0.219
I1	-	2.77	(=)	0.109
12	-	5.50	.=.:	0.217
13	-	10.40	5#3	0.409

Dimension in mm/inches



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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
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 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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